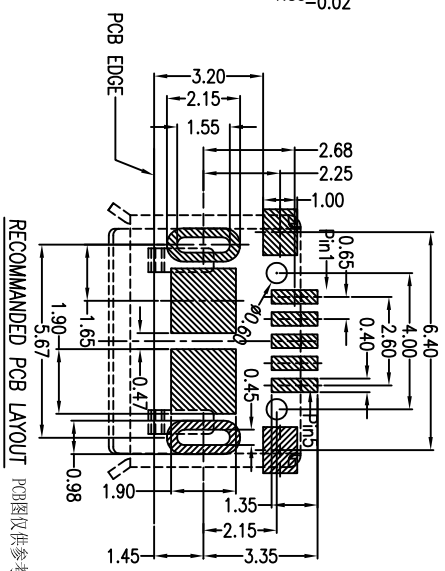
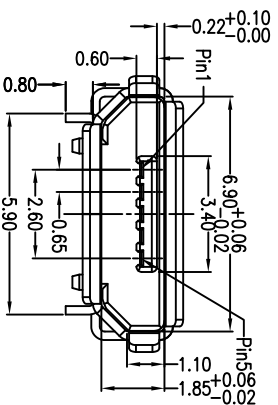
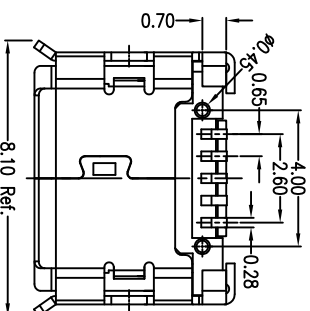
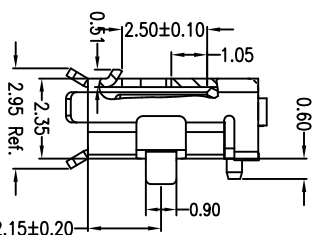
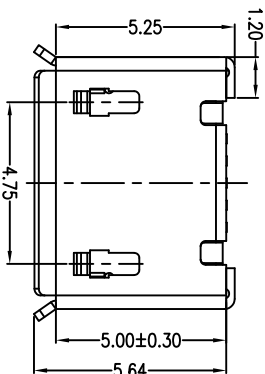
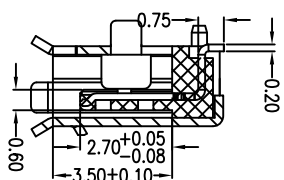
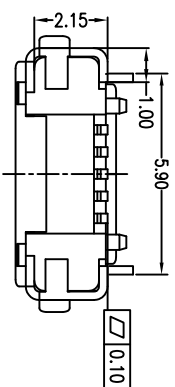


ROHS



- Note:
1. Material:
- 1.1 Housing: High temperature thermoplastic with g.f.Ul94V-0
 - 1.2 Contact: copper alloy, t=0.20mm contact area Au flash plating;
 - 1.3 Shell: copper or SUS304, t=0.25mm Sn plating 60U* min.
2. Specification:
- 2.1 Current rating: 1.5PIN 1.8A Max/2,3,4PIN 1A Max. voltage: 100 V(ac) for 1 min.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 mΩ Max.
 - 2.4 Insulation resistance: 100 MΩ Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min.
 - 2.7 Temperature range: -30°C~80°C
 - 2.8 Solderability: 90% area min.;

MAPX	MODIFICATION	DRW	DATE

产品图

公差一览表

公差一览表	单位	MM	制图	许榕强	制图料号
TOLERANCE UNLESS OTHERWISE	UNITS	MM	DRAWING	许榕强	PRODUCT PART NO.
X ±0.35	X	±0.35	审核	郭治富	产品名称
X ±0.20	X	±0.20	CHD	黄国荣	PRODUCT NO.
XX ±0.15	XX	±0.15	核准		角法
XXX ±0.05	XXX	±0.05	APPD		版本
			DATE	2016-09-09	VER

深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.